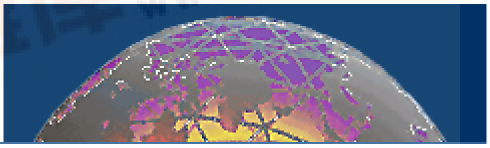
AAVID THERMALLOY



Solder Anchor Attachment Method

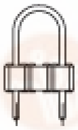
Part Number: 375124B60024
(Vis Number: 037816)

This part is in stock and available for immediate delivery:
Contact your local sales rep

BGA Surface	Interface	Heat Sink Finish	Part Class
All	T766	Black Anodize	A

Features and Benefits

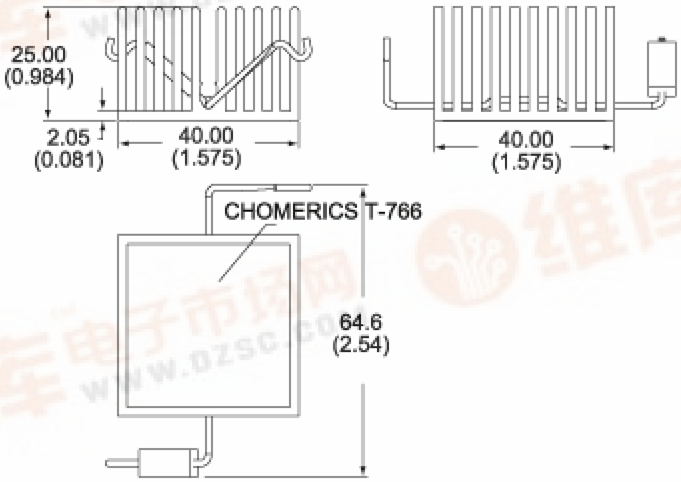
- New unique wire clip design allows for complete reworkability after assembly
- Configurations are available for a wide range of BGA package sizes in any thickness up to 3.0mm
- Minimal PC Board real estate is required for mounting
- Solder Anchors provide the most rugged mounting in the industry
- Each Heat Sink utilizes a phase change pad as the interface for optimal performance



Solder anchors are sold separately
Part Number Do57
2 Solder anchors must be soldered to the PCB Prior to attaching the heat sink clip.

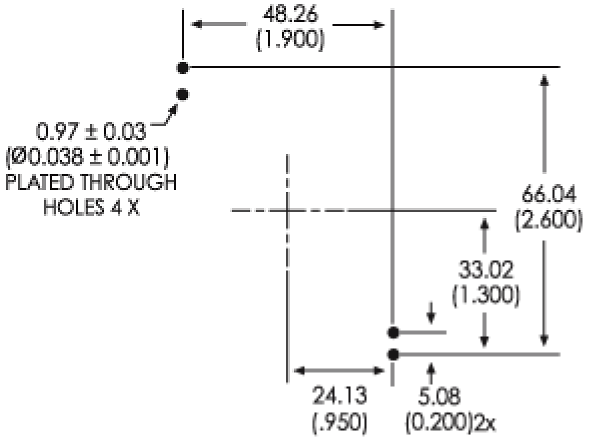
Width	Length	Height	Fin Thickness Across Width	Fin Thickness Across Length	Base Thickness	# of fins across width	# of fins across length
40mm	40mm	25mm	1.9mm	2.07mm	2.05mm	10	10

Mechanical Outline Drawing



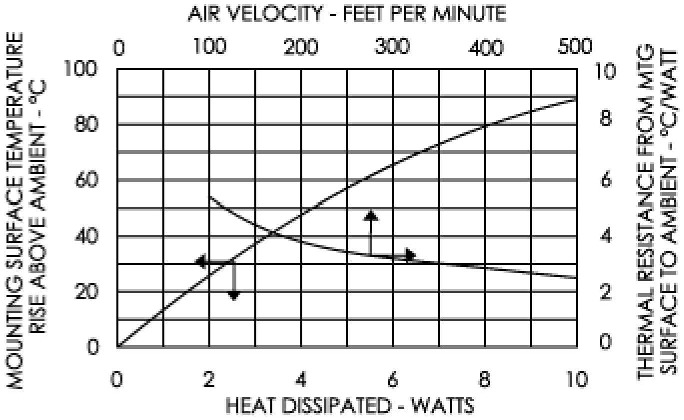
Unless otherwise shown, tolerances are ±0.38(±.015)

Recommended PCB Hole Pattern



Thermal Performance

*θn	**θf
10.3	3.83



*Natural convection thermal resistance is based on a 75 °C heat sink temperature rise.

**Forced convection thermal resistance based on an entering 1.0 m/s (200 lfm) airflow.
Due to various heat dissipation paths within a BGA device, please test the heat sink in your application.

This data sheet represents only one of a broad range of products we make to cool electronics.
Our representatives can help you configure a complete cooling solution for your individual applications.

Visit us at www.aavidthermalloy.com • info@aavid.com • ©2002 Aavid Thermalloy, LLC